Surface Roughness Measurement and Surface Smoothing via Phase-Contrast Imaging and Grayscale Lithography

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Abstract

Surface roughness can be measured by using a phase-contrast, point-imaging system to measure the surface height at a focal point relative to an average surface height across an area surrounding the point. The focal point is illuminated with an optical, point-focus probe beam, the surrounding area is illuminated with a reference beam, and the optical phase between the two beams provides the height measurement. A scanning process (e.g., raster scanning or turning) is used to construct a surface height profile over an extended area. At the same time, a surface smoothing process can be applied by a grayscale lithographic process in which a photoresistcoated surface is exposed to a laser-writing beam, which is intensity-modulated in response to the surface height measurement.

<u>Overview</u>

Advanced optical systems for applications such as extreme ultraviolet (EUV) lithography require Angstrom-scale surface form and finish tolerances over apertures up to 1 meter in size. [1] High-spatial-frequency surface roughness can be substantially eliminated with polishing, and low-spatial-frequency errors can be corrected with ion-beam finishing, but mid-spatial-frequency errors in the range of approximately 1 μ m to 1 mm cannot be easily corrected.

Optical lithography is well suited for patterning structures in the 1 μ m to 1 mm range, and lithography methods that are used for fabricating diffraction optics on curves surfaces could be adapted for surface smoothing. [2, 3] New photoresist technologies and processes similar to the LAM Research dry resist might be useful for this application. [4] The material removal for smoothing applications would be quite small, e.g., in the range of 0.1 nm to 10 nm for EUV optics, which might necessitate a relatively thin resist. However, the corrective pattern would not necessarily need to be etched directly into the substrate; it could be etched into a sacrificial layer and subsequently transferred into the substrate. The differential etch rate between the sacrificial layer and the substrate can be controlled to scale down the etch depth in a manner similar to processes that are used for synchrotron grating fabrication. [5, 6]

The lithographic exposure can be done with a laser-writing system such as a lathe-type instrument with a focused laser beam replacing the cutting tool. The exposure dose can be controlled by an interferometric surface-roughness measuring system, which measures the surface height at each point relative to an average height over an area surrounding the point. The surface profile measurement and laser writing can be done as separate, sequential processes, or could be performed concurrently, with the profile measurement controlling the laser modulation in real time.

The lithographic patterning system could be used to also correct the surface form (low-spatial-frequency errors), based on a full-aperture interferometric map of the surface shape error.

The form correction and surface smoothing can be done as separate processes, or could be done concurrently, with the interferometric measurement system providing control for smoothing while a pre-programed correction for the form error is added to the roughness correction.

Optical design

The interferometric surface-profiling system can be based on acousto-optic heterodyning, similar to the optical system described in Ref. 7, Figure 1 (with possible variations shown in Figures 5 and 6), but the optics following the optical fibers (the tool post assembly) are replaced by the apparatus illustrated in Figures 1 and 2 herein. Frequency-shifted laser radiation is conveyed to the apparatus by two polarization-preserving optical fibers – fiber 1 for the probe beam and fiber 2 for the reference beam – and the reflected radiation is conveyed back through the fibers to the detection sensors, as described in Ref. 7. The beam paths from the two fibers are merged by a polarizing beam splitter. Figure 1 illustrates a schematic ray trace from fiber 1 to the focal point on an inspection surface, and Figure 2 shows a schematic ray trace from fiber 2 to an annular illumination area surrounding the focal point. The ray traces represent bidirectional beam paths; the reflected radiation in each path is directed back into the corresponding fiber. The focusing elements are schematically illustrated as refracting lenses in Figures 1 and 2, but could have alternative forms such as planar, phase-Fresnel diffractive lenses.

Figure 3 illustrates the focus patterns on the inspection surface for the probe beam and the reference beam. The probe beam is focused onto the surface at high numerical aperture (NA) to achieve a high-resolution focus spot (Figure 1). The reference beam can be focused at low NA to increase the beam area coverage (Figure 2); in addition, a phase-modifying optical surface such as a binary diffractive axicon [8] can be interposed in the reference beam path to spread the focused illumination into an annular ring covering a larger area. The diffractive axicon is a circular, binary phase grating with a zone pattern having the form illustrated in Figure 4.

The surface is scanned, e.g., in a raster pattern or by turning it on a lathe-type instrument, to acquire profilometry data over an extended area. Accurate focus control must be maintained while scanning, and the apparatus can be adapted to provide autofocus control as illustrated in Figure 5. A partially-reflecting beam splitter is interposed in the probe beam path to divert a portion of the beam power on the return path through a focusing lens. A diffraction grating on the beam splitter divides the beam power between two foci on the lens focal plane, and two focus-sensor optical fibers are positioned at the foci. (The grating zone pattern is illustrated in Figure 6.) The fibers are slightly displaced from the focal plane, one above the plane and the other below, so that the detector signals acquired from the two fibers provide an accurate measure of focus error. The autofocus system dynamically controls the inspection surface height to keep the two signals in balance. (Other design variants for autofocus include astigmatic focus error detection. [9, 10])

The autofocus will keep the probe beam accurately in focus, but on a curved surface the reference beam will be slightly out of focus and phase-shifted due to the surface curvature. The surface height measurement at the probe point can be corrected based on the known base surface curvature. In addition, if the curvature-induce phase shift is large and varies across the reference beam, it could be advantageous to correct it optically by incorporating focus control in the

reference beam path. One or more lens elements in the reference beam path can be moved to compensate for non-flatness of the inspection surface, including asymmetric (e.g., saddle-shape) curvature.

The optics can be further adapted to perform laser writing on a photoresist-coated surface concurrently with surface profile height sensing. The exposure beam, from a modulated laser source, can be merged into the probe beam's optical path by means of a dichroic beam splitter as illustrated in Figure 7. Typically, a short-wavelength laser (blue or UV) would be used for exposure while a longer wavelength, which does not affect the resist, is used for surface profiling. The surface profile data is used to control the exposure laser intensity to effect surface smoothing via grayscale lithography. In the Figure 7 schematic the exposure wavelength is brought to a focus at a point coinciding with the profilometer's measurement probe point, but it could alternatively be displaced from the measurement point to allow for a data processing delay between the time a surface point is measured and the time it is exposed.

References

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Figure 1











Figure 7